



PART NO. : TG111-HPE2NWLF

DESIGNED FOR DUAL-PORT GIGABIT OR QUAD-PORT FAST ETHERNET APPLICATIONS

COMPLIANT TO IEEE802.3at STANDARD FOR PoE+, 600mADC CURRENT PER PAIR

LEAD-FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

EXTENDED OPERATING TEMPERATURE -40/+85°C

ELECTRICAL SPECIFICATIONS @ 25°C

URNS RATIO 1CT:1CT $\pm 2\%$

OCL (100KHz,0.1V)

11mADC

19mADC

350 μ H min

120 μ H min

INSERTION LOSS

1-100MHz

-1.1dB max

RETURN LOSS

1-40MHz

-18dB min

60MHz

-14dB min

80MHz

-12dB min

100MHz

-10dB min

CMR

1-100MHz

-40dB typ

CROSSTALK

1-30MHz

-50dB typ

60MHz

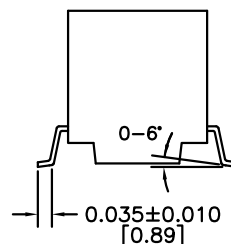
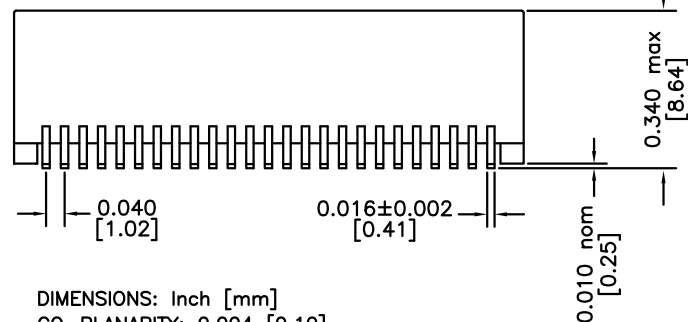
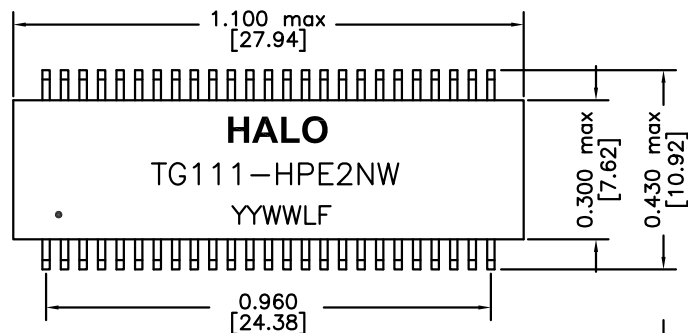
-45dB typ

100MHz

-40dB typ

ISOLATION

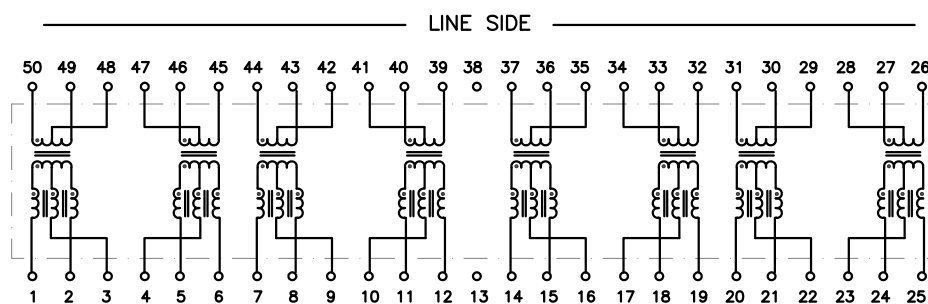
1,500Vrms



DIMENSIONS: Inch [mm]

CO-PLANARITY: 0.004 [0.10]

TOLERANCES: ± 0.005 INCH IF NOT SPECIFIED



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE ISOLATION MODULE

FOR GIGABIT/FAST ETHERNET, PoE+

PART NO. TG111-HPE2NWLF

SCALE NONE

PAGE 1 OF 2

SIGNATURES

DRAWN LI ZHI ZHONG

CHECKED LEI KEONG

APPROVED PETER LU

FILE HPE2NWLF.DWG

DATE

7/15/14

10/30/19

10/30/19

REV.

A

B

DESC.

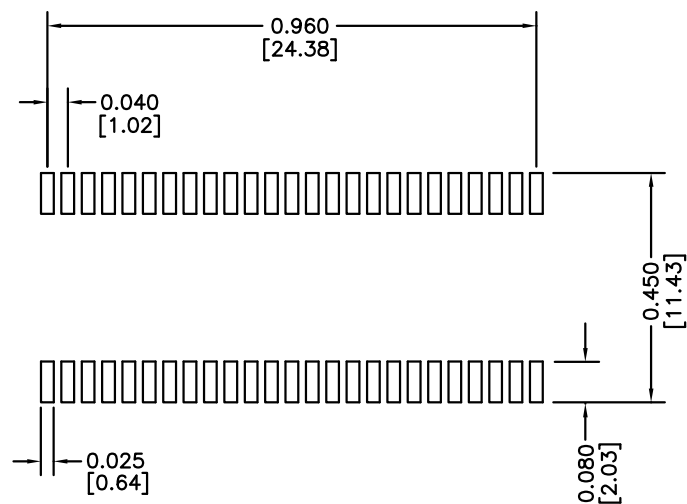
FIRST ISSUE

PROD. RELEASE

DATE

7/15/14

10/30/19



RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES		DATE	REV.	DESC.	DATE
	FOR		DRAWN	LI ZHI ZHONG	7/15/14	A	FIRST ISSUE	7/15/14
	PART NO.		CHECKED	LEI KEONG	10/30/19	B	PROD. RELEASE	10/30/19
	TG111-HPE2NWLF		APPROVED	PETER LU	10/30/19			
SCALE	NONE	PAGE	2 of 2		FILE	HPE2NWLF.DWG		